Sub

Sn, the balance of the alloy consisting of Cu, is bonded to a backing metal, and has on its side opposite to the backing metal a roughened surface of approximately 0.5 to approximately $10 \mu m$ of roughness (Rz);

said roughened surface is coated with a coating layer comprising at least one thermo-setting resin, which is selected from the group consisting of polyimide resin, polyamide-imide resin, epoxy resin and phenol resin, and which contains from 55 to 95% by weight of MoS₂, and wherein said roughened surface is formed of grooves extending in the sliding direction;

Ag and Sn are solid-dissolved in the Cu matrix of the copper alloy in at least the vicinity of said roughened surface where essentially no secondary phase of Ag or Sn is formed;

and, one of:

said Ag and Sn,

a hexagonal compound of Ag and Sn,

a hexagonal compound of Cu and Ag and Sn, or

a eutectic of Ag and Sn, or a eutectic of Cu and Ag and Sn;

is present in a higher concentration in a portion of a sub-layer of the alloy than in the alloy nearest said backing metal.

2. (Amended) A sliding bearing according to Claim 1, characterized in that said copper alloy further comprises 10% by weight or less of at least one additive element selected from the group consisting of Sb, In, Al, Mg and Cd; said Ag and Sn and said at least one additive element are solid-dissolved in the Cu matrix of the copper alloy in at least the vicinity of said roughened surface where

Sub Ton

essentially no secondary phase of Ag or Sn or said at least one additive element is formed; and wherein said one of:

said Ag and Sn,

said hexagonal compound, or

said eutectic;

present in a higher concentration in a portion of the sub-layer further comprises said at least one additive element.

11. (New) A sliding bearing according to claim 1, wherein said Ag and Sn, said hexagonal compound, or said eutectic is present in a portion of the sub-layer in a concentration that is at least 1.3 times higher than in the alloy nearest said backing metal.

12. (New) A sliding bearing according to claim 2, wherein said Ag and Sn and said at least one additive element, said hexagonal compound, or said eutectic is present in a portion of the sublayer in a concentration that is at least 1.3 times higher than in the allow nearest said backing metal.

REMARKS

Claims 1, 2, 4-7, 9-12 are pending in the present application. Claim 3 and 8 have been canceled. New Claims 11 and 12 have been added, which find support in the specification on page 10, lines19-21.

Specification